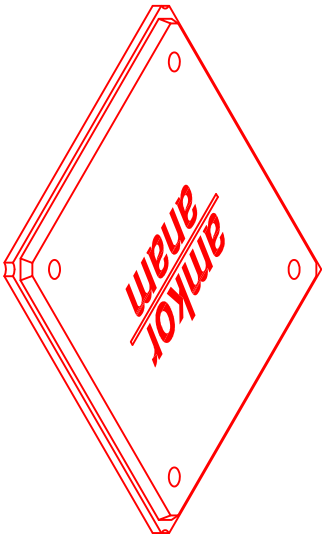


REV		DESCRIPTION	DATE	CHECKED	OWNED BY
00	INITIAL	RELEASE PER DCN C05751	04/05/99	IGHAN	DRA
01	MOLD CAP WAS 38.00mm, DCN C06251	05/19/99	IGHAN	DRA	

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8. REFERENCE SPECIFICATIONS:
- A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 - B. AAWW SPEC #001-0519-2062: MARKING.
 - C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE NO-151/D VARIATION BAU-2.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 900.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 30 X 30.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.27mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS		PRODUCTION		TITLE	
DECIMAL	ANGULAR	APPROVALS	DATE	DATE	DATE
XXX ±0.10	±1°	DRAWN D. BRIGGS	01/28/99	PACKAGE OUTLINE - PBGA CUSTOM, 30 X 30, 40.0mm X 40.0mm, 1.17mm CAP, MULTILAYER, 1.27mm PITCH, LAMINATE SUBSTRATE, AAWW	01/28/99
XXX ±0.05		CHECKED D. ANNOLD	01/28/99	SIZE 75214	01
X.XXX ±0.03		DATE B. DOOLIE	01/28/99	DATE 75214	01
		DATE C. SCHULTZ	04/03/99	SCALE: 4:1	SHEET 1 OF 3

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